

SN54ALS243A, SN74ALS243A QUADRUPLE BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS069B – DECEMBER 1982 – REVISED DECEMBER 1994

- Two-Way Asynchronous Communication Between Data Buses
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

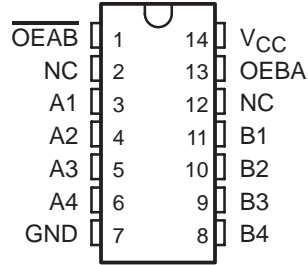
description

These quadruple bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing. These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable ($\overline{\text{OEBA}}$ and $\overline{\text{OEAB}}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

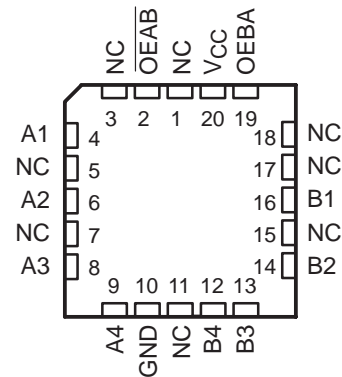
The dual-enable configuration gives the quadruple bus transceivers the capability to store data by simultaneously enabling $\overline{\text{OEBA}}$ and $\overline{\text{OEAB}}$. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (eight in all) retain their states. The 4-bit codes appearing on the two sets of buses are identical.

The SN54ALS243A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS243A is characterized for operation from 0°C to 70°C .

SN54ALS243A . . . J PACKAGE
SN74ALS243A . . . D OR N PACKAGE
(TOP VIEW)



SN54ALS243A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

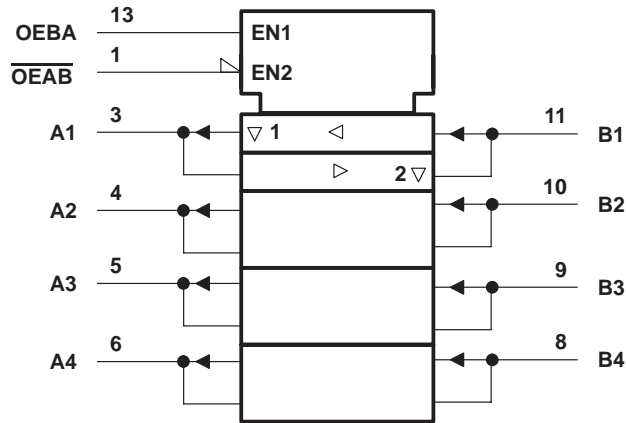
FUNCTION TABLE

INPUTS		FUNCTION
$\overline{\text{OEAB}}$	$\overline{\text{OEBA}}$	
L	L	A to B
H	H	B to A
H	L	Isolation
L	H	Latch A and B (A = B)

SN54ALS243A, SN74ALS243A QUADRUPLE BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

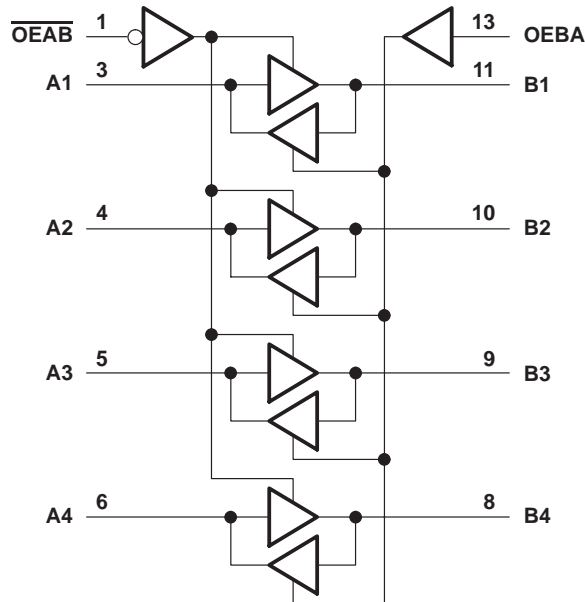
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T_A : SN54ALS243A	–55°C to 125°C
SN74ALS243A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS243A			SN74ALS243A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			–12			–15	mA
I_{OL}	Low-level output current			12			24	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

SN54ALS243A, SN74ALS243A QUADRUPLE BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS243A		SN74ALS243A		UNIT
				MIN	TYP†	MAX	MIN	
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA		−1.2		−1.2		V
V _{OH}		V _{CC} = 4.5 V to 5.5 V, I _{OH} = −0.4 mA		V _{CC} − 2		V _{CC} − 2		V
		V _{CC} = 4.5 V	I _{OH} = −3 mA	2.4	3.2	2.4	3.2	
			I _{OH} = −12 mA	2				
			I _{OH} = −15 mA			2		
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 12 mA	0.25	0.4	0.25	0.4	V
			I _{OL} = 24 mA			0.35	0.5	
I _I	Control inputs	V _{CC} = 5.5 V	V _I = 7 V	0.1		0.1		mA
	A or B ports		V _I = 5.5 V	0.1		0.1		
I _{IH}	Control inputs	V _{CC} = 5.5 V, V _I = 2.7 V	20		20		μA	
	A or B ports‡		20		20			
I _{IL}	Control inputs	V _{CC} = 5.5 V, V _I = 0.4 V	−0.1		−0.1		mA	
	A or B ports‡		−0.1		−0.1			
I _O §		V _{CC} = 5.5 V, V _O = 2.25 V	−20	−112	−30	−112	mA	
I _{CC}		V _{CC} = 5.5 V	Outputs high	15	30	15	25	mA
			Outputs low	20	35	20	30	
			Outputs disabled	21	37	21	32	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC = 4.5 V to 5.5 V, CL = 50 pF, R1 = 500 Ω, R2 = 500 Ω, TA = MIN to MAX†				UNIT
			SN54ALS243A		SN74ALS243A		
			MIN	MAX	MIN	MAX	
tPLH	A or B	B or A	4	15	4	11	ns
tPHL			4	15	4	11	
tPZH	$\overline{\text{OEAB}}$	B	7	25	7	20	ns
tPZL			7	25	7	20	
tPHZ	$\overline{\text{OEAB}}$	B	2	16	2	14	ns
tPLZ			3	27	3	22	
tPZH	OEBA	A	7	25	7	20	ns
tPZL			7	25	7	20	
tPHZ	OEBA	A	2	16	2	14	ns
tPLZ			3	27	3	22	

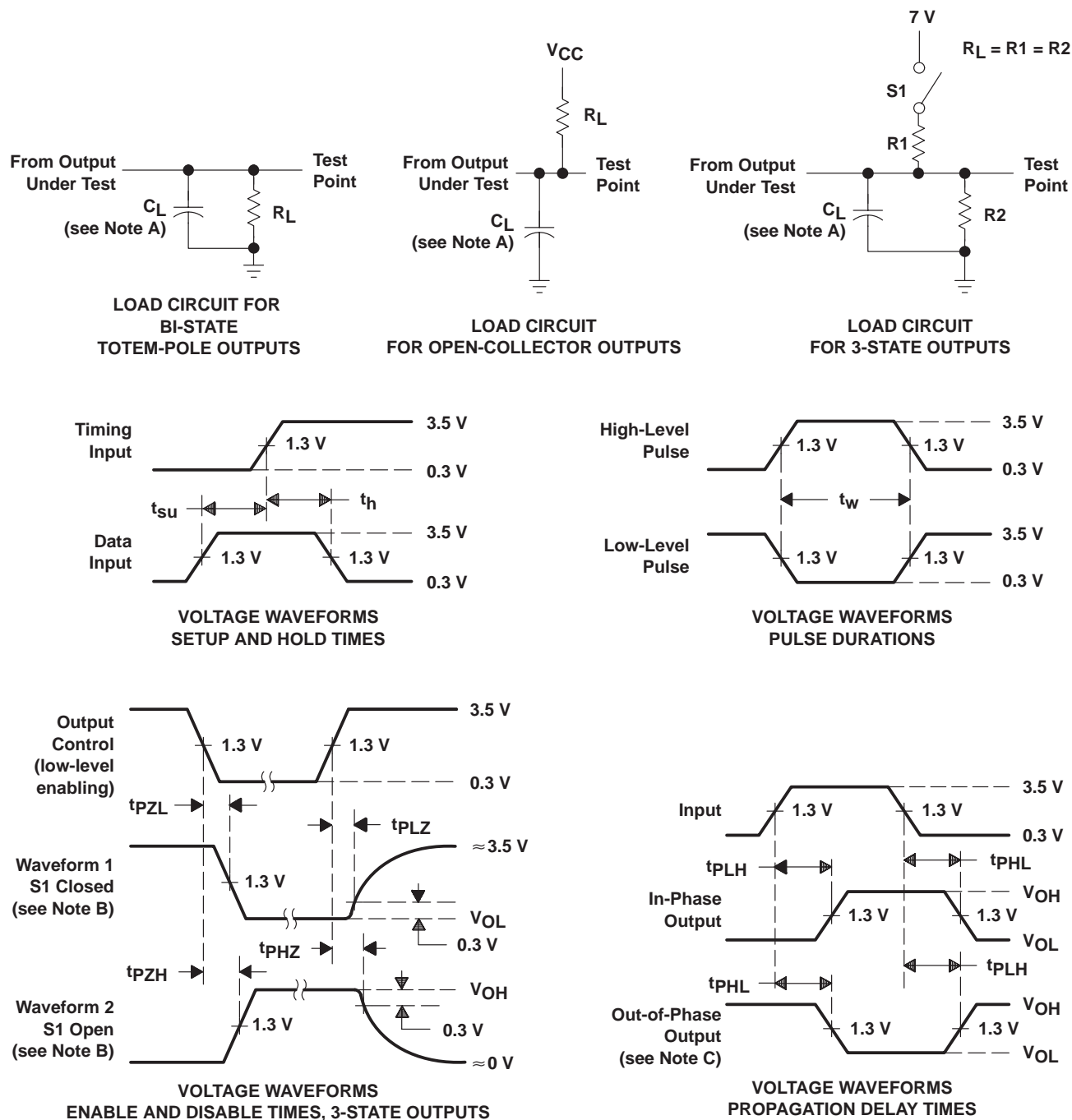
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS243A, SN74ALS243A QUADRUPLE BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS069B – DECEMBER 1982 – REVISED DECEMBER 1994

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84013022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84013022A SNJ54ALS 243AFK	Samples
8401302CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401302CA SNJ54ALS243AJ	Samples
8401302DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401302DA SNJ54ALS243AW	Samples
SN74ALS243A-1N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74ALS243AD	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SN74ALS243ADE4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SN74ALS243ADG4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SN74ALS243AN	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS243AN	
SN74ALS243ANE4	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS243AN	
SN74ALS243ANSR	NRND	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SN74ALS243ANSRE4	NRND	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SN74ALS243ANSRG4	NRND	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS243A	
SNJ54ALS243AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84013022A SNJ54ALS 243AFK	Samples
SNJ54ALS243AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401302CA SNJ54ALS243AJ	Samples
SNJ54ALS243AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401302DA SNJ54ALS243AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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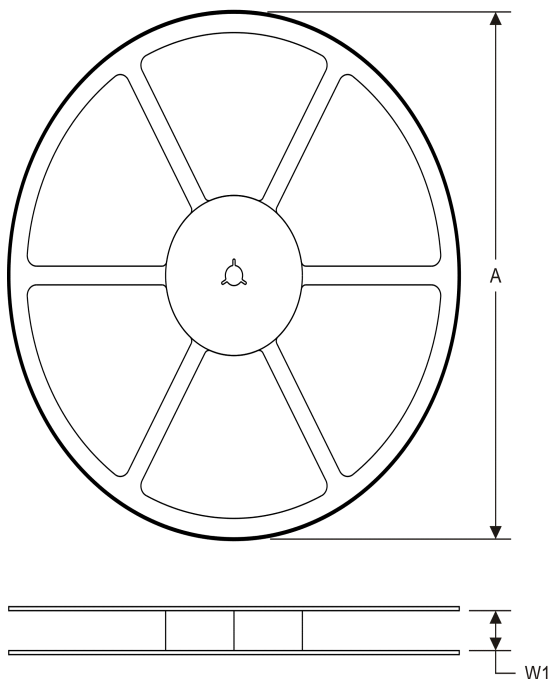
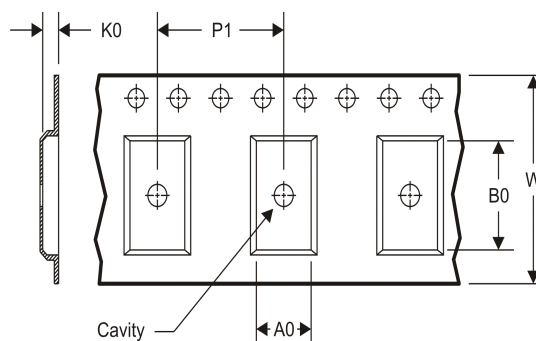
OTHER QUALIFIED VERSIONS OF SN54ALS243A, SN74ALS243A :

● Catalog: [SN74ALS243A](#)

● Military: [SN54ALS243A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


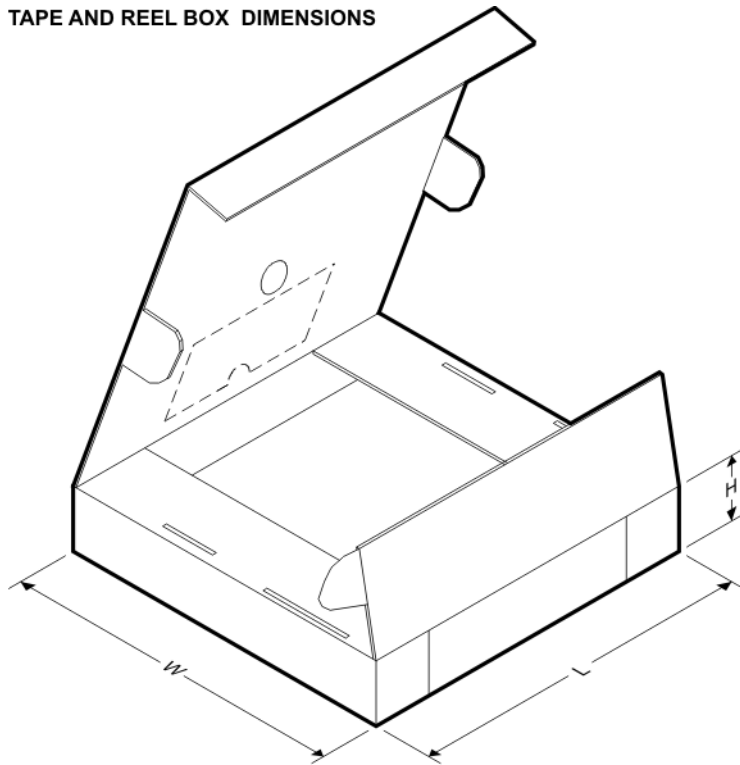
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS243ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



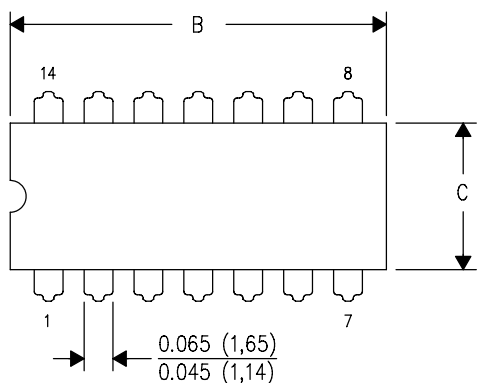
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS243ANSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

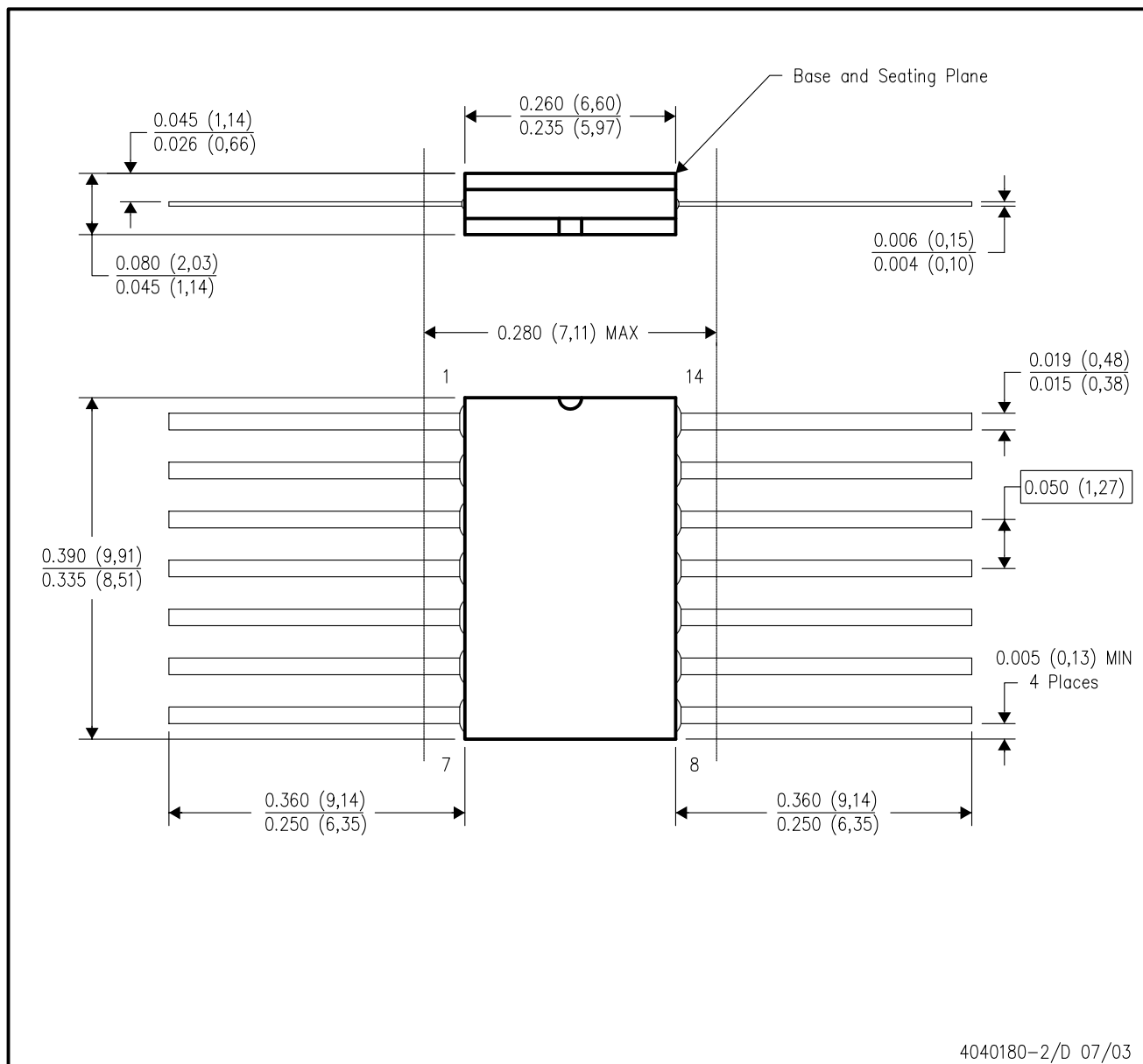


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

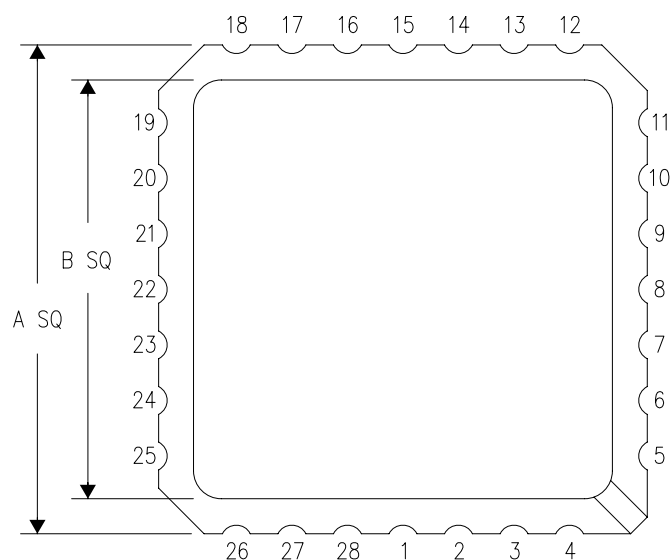


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

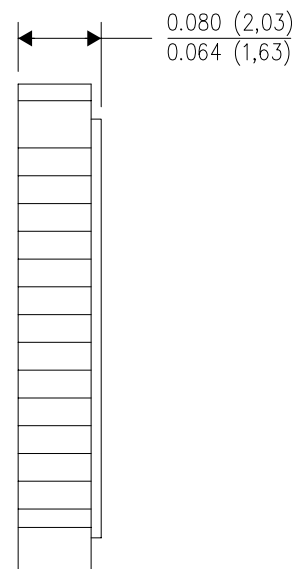
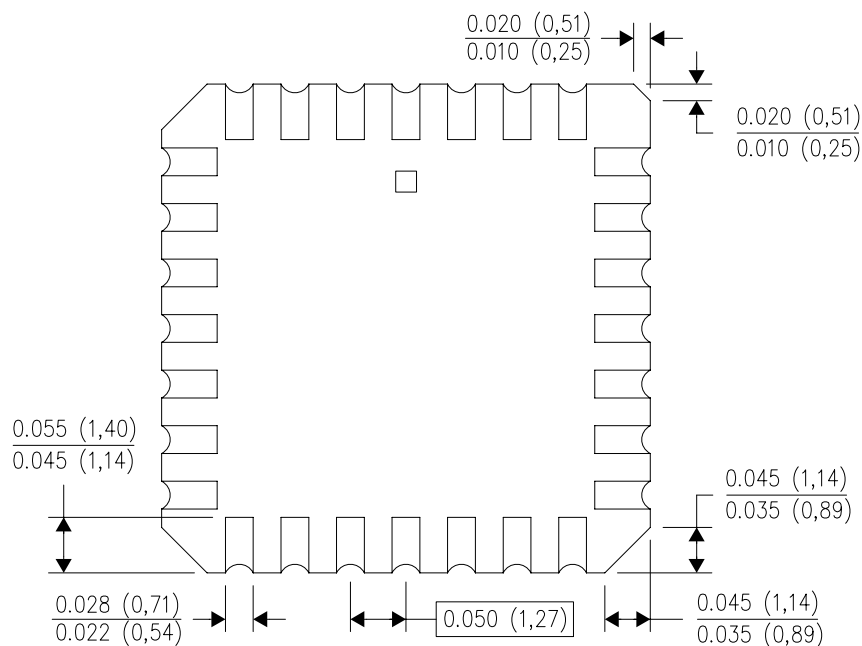
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



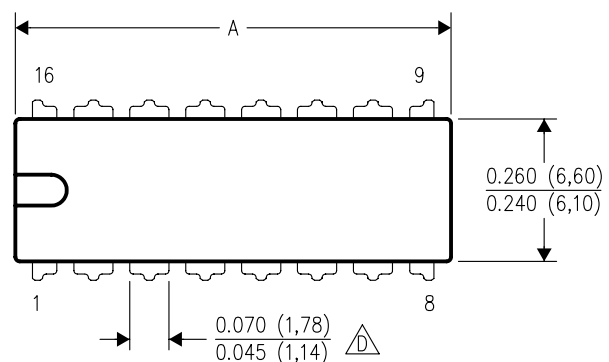
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

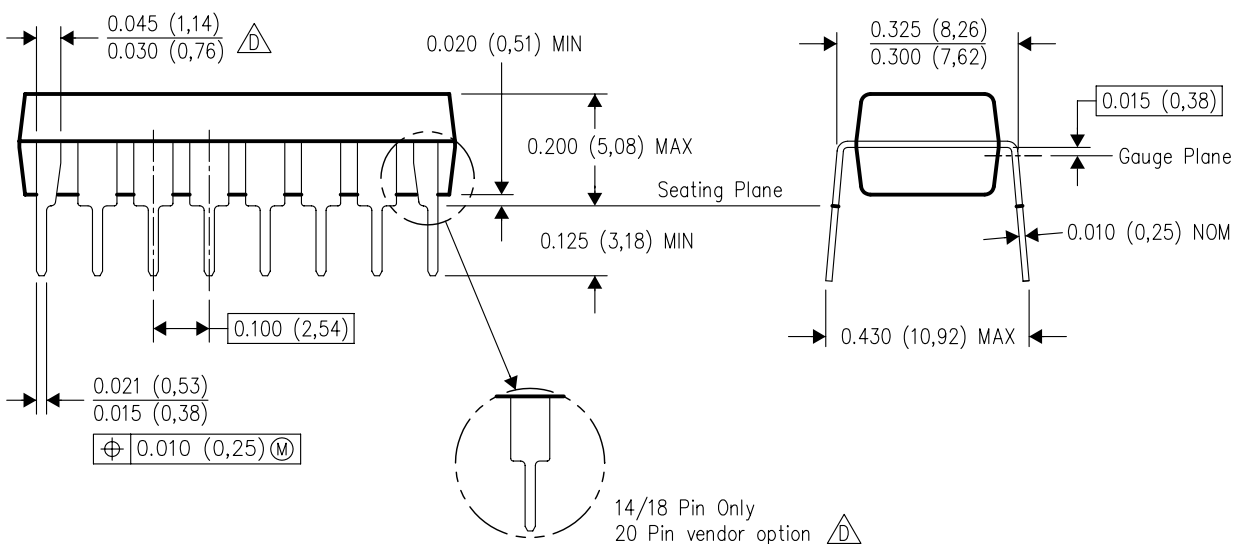
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE





PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



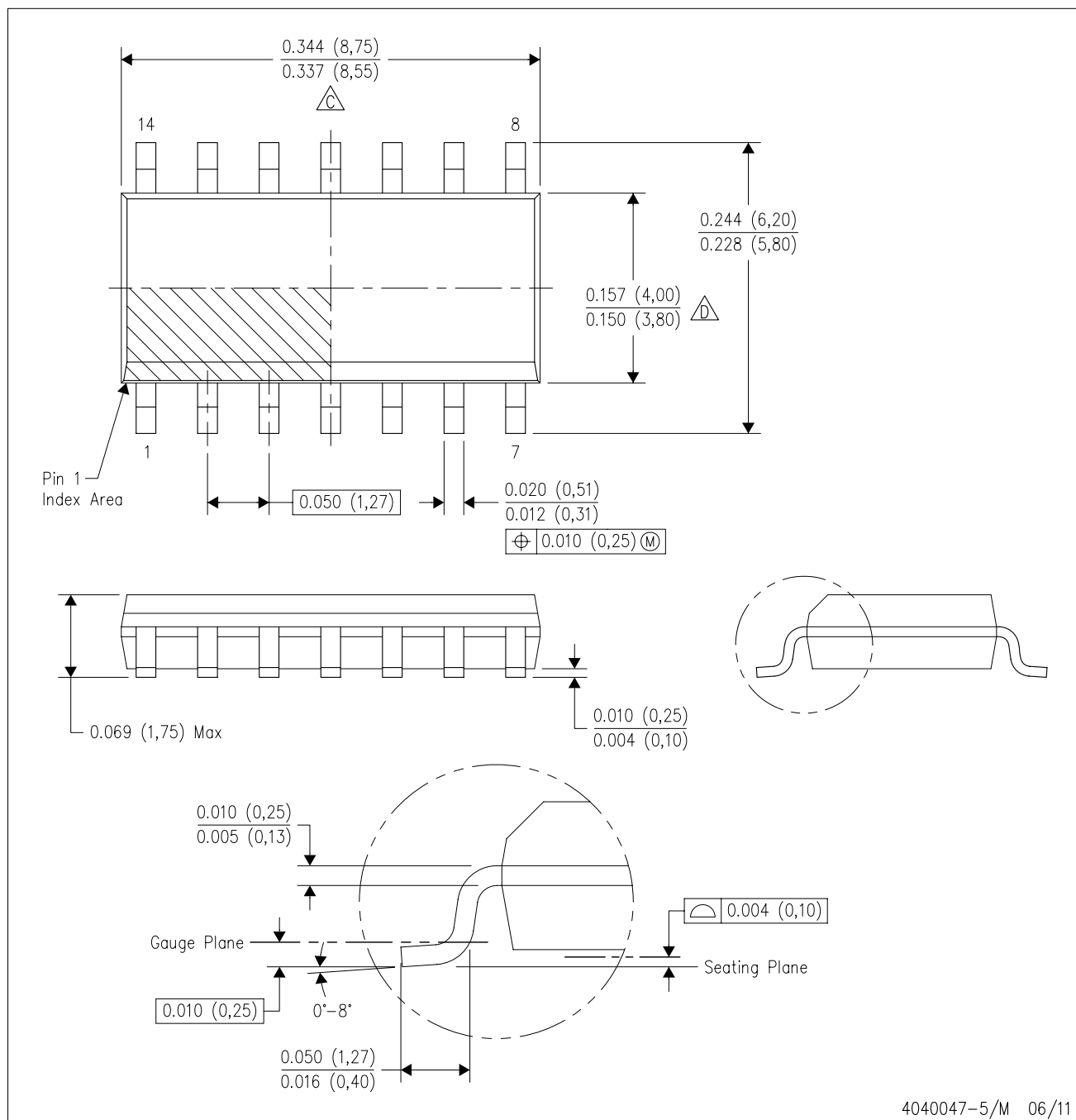
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



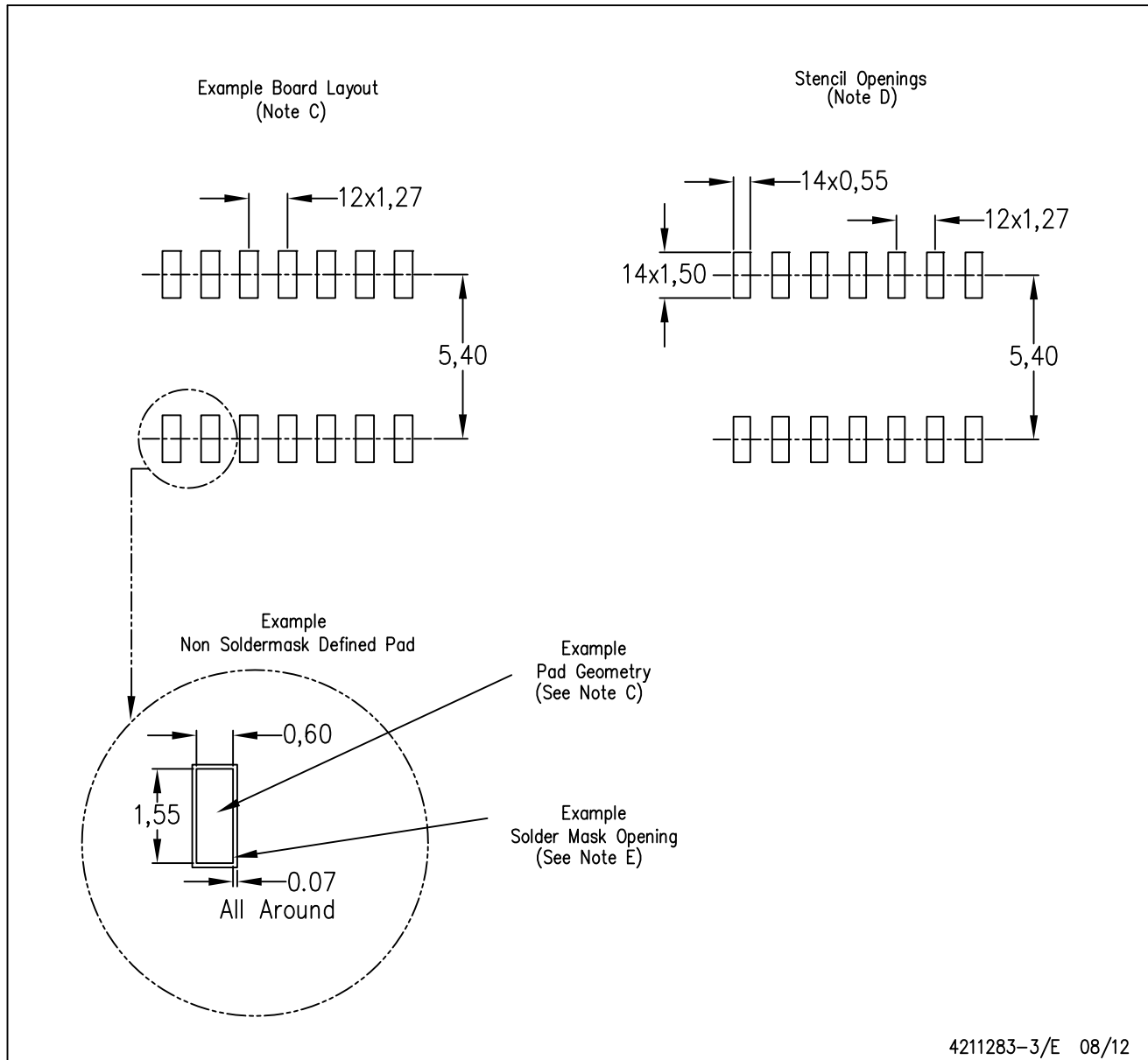
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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